

Rev. V1

Designed for broadband commercial and military applications at frequencies to 175 MHz. The high power, high gain and broadband performance of this device is especially useful for FM broadcast or TV channel frequency band solid state transmitters and amplifiers.

Guaranteed performance at 175MHz, 28V:

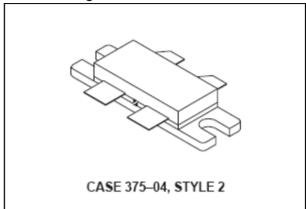
Output power: 300W Gain: 12dB (14dB Typ.) Efficiency: 50%

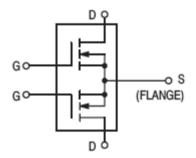
Low thermal resistance: 0.35°C/W

Ruggedness tested at rated output power

• Nitride passivated die for enhanced reliability

# **Product Image**





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Information in this document is provided in connection with M/A COM Technology Solutions Inc ("MACOM")
MAXIMUM RATINGS

Rating	Syr	mbol	Value	Unit
Drain-Source Voltage	V	oss	65	Vdc
Drain-Gate Voltage	V <sub>C</sub>	OGO	65	Vdc
Gate-Source Voltage	V	gs	±40	Vdc
Drain Current — Continuous		I <sub>D</sub>	32	Adc
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	F	P <sub>D</sub>	500 2.85	Watts W/∘C
Storage Temperature Range	Т	stg	-65 to +150	°C
Operating Junction Temperature	-	TJ	200	°C

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R <sub>eJC</sub>	0.35	°C/W

NOTE — <u>CAUTION</u> — MOS devices are susceptible to damage from electrostatic charge. Reasonable precautions in handling and packaging MOS devices should be observed.

fully indemnify MACOM for any damages resulting from such improper use or sale.

1

# **MRF141G**



RF Power FET 300W, 175MHz, 28V

Rev. V1

## ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS (1)					
Drain–Source Breakdown Voltage (V <sub>GS</sub> = 0, I <sub>D</sub> = 100 mA)	V <sub>(BR)DSS</sub>	65	_	_	Vdc
Zero Gate Voltage Drain Current (V <sub>DS</sub> = 28 V, V <sub>GS</sub> = 0)	I <sub>DSS</sub>	_	_	5.0	mAdc
Gate–Body Leakage Current (V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0)	I <sub>GSS</sub>	_	_	1.0	μAdc
ON CHARACTERISTICS (1)					
Gate Threshold Voltage (V <sub>DS</sub> = 10 V, I <sub>D</sub> = 100 mA)	V <sub>GS(th)</sub>	1.0	3.0	5.0	Vdc
Drain–Source On–Voltage (V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A)	V <sub>DS(on)</sub>	0.1	0.9	1.5	Vdc
Forward Transconductance (V <sub>DS</sub> = 10 V, I <sub>D</sub> = 5.0 A)	9 <sub>fs</sub>	5.0	7.0	_	mhos
DYNAMIC CHARACTERISTICS (1)	•		•	•	•
Input Capacitance (V <sub>DS</sub> = 28 V, V <sub>GS</sub> = 0, f = 1.0 MHz)	C <sub>iss</sub>	_	350	_	pF
Output Capacitance (V <sub>DS</sub> = 28 V, V <sub>GS</sub> = 0, f = 1.0 MHz)	C <sub>oss</sub>	_	420	_	pF
Reverse Transfer Capacitance (V <sub>DS</sub> = 28 V, V <sub>GS</sub> = 0, f = 1.0 MHz)	C <sub>rss</sub>	_	35	_	pF
FUNCTIONAL TESTS (2)	•		•	•	•
Common Source Amplifier Power Gain (V <sub>DD</sub> = 28 V, P <sub>out</sub> = 300 W, I <sub>DQ</sub> = 500 mA, f = 175 MHz)	G <sub>ps</sub>	12	14	_	dB
Drain Efficiency (V <sub>DD</sub> = 28 V, P <sub>out</sub> = 300 W, f = 175 MHz, I <sub>D</sub> (Max) = 21.4 A)	η	45	55	_	%
Load Mismatch (V <sub>DD</sub> = 28 V, P <sub>out</sub> = 300 W, I <sub>DQ</sub> = 500 mA, f = 175 MHz, VSWR 5:1 at all Phase Angles)	Ψ	No Degradation in Output Power			

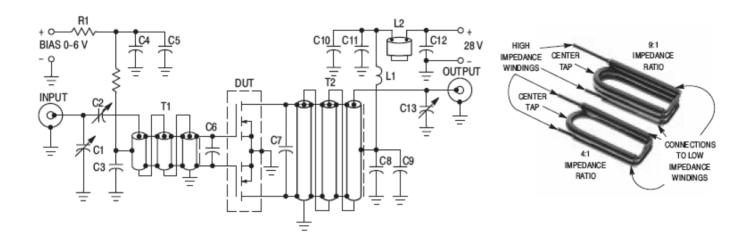
# NOTES:

Each side measured separately.

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Rev. V1



C1 - Arco 402, 1.5-20 pF

C2 - Arco 406, 15-115 pF

C3, C4, C8, C9, C10 — 1000 pF Chip

C5, C11 - 0.1 µF Chip

C6 - 330 pF Chip

C7 - 200 pF and 180 pF Chips in Parallel

C12 — 0.47 µF Ceramic Chip, Kemet 1215 or Equivalent

C13 — Arco 403, 3.0-35 pF

L1 — 10 Turns AWG #16 Enameled Wire.

Close Wound, 1/4" I.D.

L2 - Ferrite Beads of Suitable Material for

1.5-2.0 µH Total Inductance

R1 — 100 Ohms, 1/2 W

R2 — 1.0 kOhm, 1/2 W

T1 — 9:1 RF Transformer. Can be made of 15-18 Ohms Semirigid Co-Ax, 62-90 Mils O.D.

T2 — 1:9 RF Transformer. Can be made of 15-18 Ohms Semirigid Co-Ax, 70-90 Mils O.D.

Board Material — 0.062" Fiberglass (G10),

1 oz. Copper Clad, 2 Sides,  $\varepsilon_r = 5$ 

NOTE: For stability, the input transformer T1 must be loaded with ferrite toroids or beads to increase the common mode inductance. For operation below 100 MHz. The same is required for the output transformer.

See pictures for construction details.

Unless Otherwise Noted, All Chip Capacitors are ATC Type 100 or Equivalent.

# Figure 1. 175 MHz Test Circuit

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Rev. V1

#### TYPICAL CHARACTERISTICS

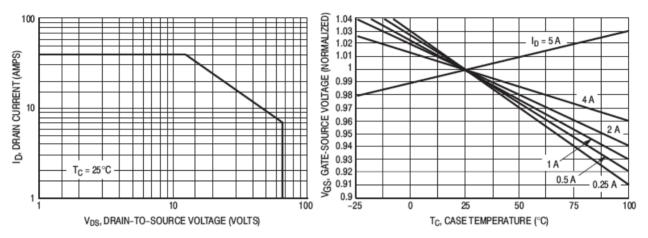


Figure 2. DC Safe Operating Area

Figure 3. Gate-Source Voltage versus

Case Temperature

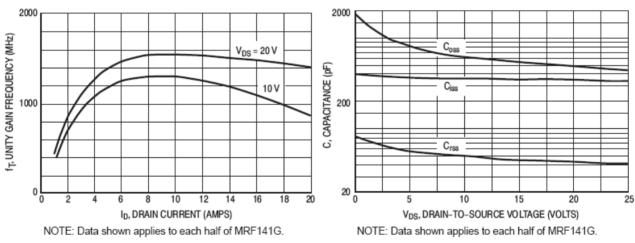


Figure 4. Common Source Unity Gain Frequency versus Drain Current

Figure 5. Capacitance versus Drain-Source Voltage

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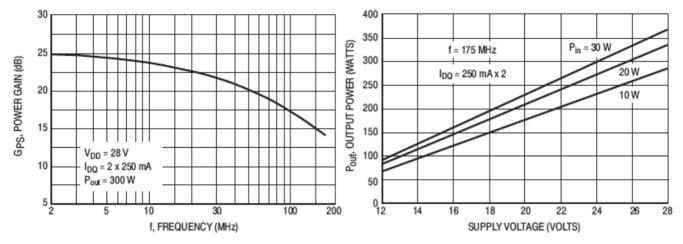


Figure 6. Power Gain versus Frequency

Figure 7. Output Power versus Supply Voltage

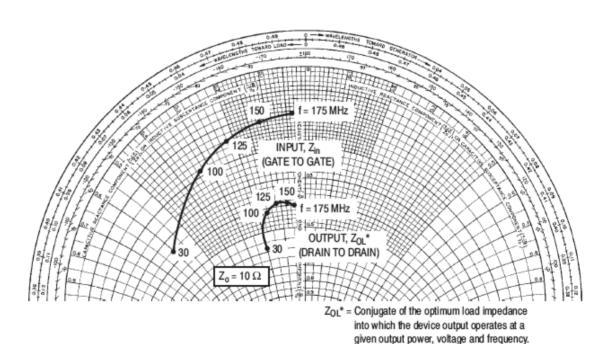


Figure 8. Input and Output Impedances

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Rev. V1

NOTE: S-Parameter data represents measurements taken from one chip only.

Table 1. Common Source S-Parameters ( $V_{DS}$  = 24 V,  $I_{D}$  = 0.57 A)

f	S	s <sub>21</sub>		S <sub>12</sub>		12	S	<b>S</b> <sub>22</sub>	
MHz	S <sub>11</sub>	∠ φ	S <sub>21</sub>	∠ φ	S <sub>12</sub>	∠ ф	S <sub>22</sub>	∠ φ	
30	0.845	-174	4.88	78	0.014	-5	0.939	-174	
40	0.867	-174	3.23	66	0.013	-14	0.856	-172	
50	0.876	-174	2.62	62	0.013	-17	0.868	-175	
60	0.883	-174	2.12	59	0.012	-15	0.938	-176	
70	0.890	-175	1.85	58	0.012	-12	1.036	-177	
80	0.899	-175	1.57	56	0.011	-10	1.110	-177	
90	0.909	-175	1.36	50	0.010	-11	1.190	-176	
100	0.920	-176	1.13	43	0.009	-13	1.160	-176	
110	0.930	-176	0.95	37	0.007	-16	1.100	-177	
120	0.938	-176	0.78	33	0.007	-11	1.010	-175	
130	0.944	-176	0.67	31	0.006	-3	0.954	-176	
140	0.948	-177	0.60	31	0.006	10	0.964	-177	
150	0.951	-177	0.56	32	0.005	23	1.023	-178	
160	0.954	-178	0.52	32	0.005	31	1.130	-179	
170	0.958	-178	0.48	29	0.006	37	1.190	-178	
180	0.962	-178	0.45	24	0.006	39	1.260	-179	
190	0.965	-179	0.40	17	0.007	41	1.200	180	
200	0.968	-179	0.34	15	0.008	49	1.090	-179	
210	0.970	-179	0.30	15	0.008	60	0.980	-178	
220	0.972	-180	0.27	15	0.008	68	0.960	-177	
230	0.973	-180	0.25	17	0.008	68	1.045	-179	
240	0.974	180	0.24	20	0.009	67	1.030	179	
250	0.975	180	0.24	19	0.011	68	1.100	179	
260	0.977	179	0.21	17	0.012	69	1.200	179	
270	0.978	179	0.22	13	0.013	72	1.210	177	
280	0.979	179	0.19	13	0.012	72	1.170	177	
290	0.979	178	0.17	1	0.012	68	1.040	180	

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Rev. V1

Table 1. Common Source S-Parameters (VDS = 24 V, ID = 0.57 A) (continued)

f	S <sub>11</sub>		S <sub>21</sub>		S	S <sub>12</sub>		S <sub>22</sub>	
MHz	S <sub>11</sub>	∠ φ	S <sub>21</sub>	∠ φ	S <sub>12</sub>	∠ φ	S <sub>22</sub>	∠ φ	
300	0.980	178	0.16	8	0.013	65	0.998	179	
310	0.980	178	0.16	13	0.015	70	0.977	179	
320	0.981	178	0.16	15	0.017	76	0.979	178	
330	0.982	177	0.13	10	0.017	83	1.033	178	
340	0.982	177	0.15	19	0.016	81	1.110	176	
350	0.982	177	0.13	16	0.016	73	1.140	177	
360	0.983	177	0.13	8	0.020	63	1.150	177	
370	0.982	176	0.10	6	0.023	65	1.120	176	
380	0.982	176	0.10	7	0.023	72	1.050	177	
390	0.982	176	0.10	10	0.021	81	0.993	177	
400	0.982	176	0.09	14	0.018	83	0.959	179	
410	0.983	175	0.10	12	0.020	71	1.040	176	
420	0.983	175	0.09	16	0.025	65	1.090	174	
430	0.984	175	0.09	15	0.028	70	1.100	174	
440	0.983	174	0.09	12	0.028	77	1.100	175	
450	0.983	174	0.09	13	0.025	82	1.090	176	
460	0.983	174	0.07	14	0.022	66	1.080	174	
470	0.983	174	0.07	13	0.024	56	0.992	175	
480	0.983	174	0.07	16	0.032	60	0.970	175	
490	0.984	173	0.07	13	0.036	74	0.996	174	
500	0.984	173	0.07	18	0.035	85	1.040	174	

Table 2. Common Source S-Parameters ( $V_{DS}$  = 28 V,  $I_{D}$  = 0.65 A)

f	f S <sub>11</sub>		S	21	S	S <sub>12</sub>		22
MHz	S <sub>11</sub>	∠ φ	S <sub>21</sub>	∠ φ	S <sub>12</sub>	∠ φ	S <sub>22</sub>	∠ ф
30	0.849	-174	5.41	79	0.013	-6	0.934	-174
40	0.869	-174	3.59	67	0.013	-16	0.849	-172
50	0.878	-174	2.91	62	0.012	-17	0.859	-174
60	0.884	-174	2.36	60	0.011	-13	0.928	-176
70	0.890	-175	2.06	59	0.010	-11	1.029	-177
80	0.899	-175	1.75	56	0.009	-14	1.110	-177
90	0.910	-176	1.52	51	0.009	-18	1.190	-175
100	0.920	-176	1.26	43	0.009	-19	1.150	-175
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Rev. V1

Table 2. Common Source S-Parameters (VDS = 28 V, ID = 0.65 A) (continued)

110	0.929	-176	1.07	37	0.008	-15	1.100	-177
120	0.937	-176	0.88	34	0.006	-4	1.000	-175
130	0.943	-176	0.75	32	0.004	5	0.953	-176
140	0.947	-177	0.67	32	0.003	6	0.966	-177
150	0.950	-177	0.63	32	0.004	6	1.030	-178
160	0.953	-178	0.58	32	0.005	18	1.120	-178
170	0.957	-178	0.54	29	0.006	36	1.180	-178
180	0.961	-178	0.51	24	0.006	53	1.250	-179
190	0.964	-179	0.45	18	0.006	65	1.200	180
200	0.967	-179	0.39	15	0.005	69	1.110	-179
210	0.969	-179	0.35	15	0.005	63	1.030	-178
220	0.971	-180	0.31	15	0.006	59	0.975	-177
230	0.972	-180	0.28	17	0.009	66	1.040	-179
240	0.973	180	0.27	20	0.010	78	1.030	179
250	0.974	180	0.27	19	0.010	88	1.090	180
260	0.976	179	0.24	17	0.009	85	1.200	179
270	0.977	179	0.24	12	0.010	73	1.220	177
280	0.978	179	0.21	12	0.011	66	1.170	178
290	0.979	178	0.19	2	0.013	70	1.040	180
300	0.979	178	0.18	8	0.013	78	1.000	179
310	0.979	178	0.17	13	0.013	89	0.975	179
320	0.980	178	0.17	14	0.012	88	0.988	177
330	0.981	177	0.14	9	0.013	80	1.050	177
340	0.982	177	0.16	17	0.015	75	1.110	176
350	0.982	177	0.15	14	0.018	80	1.130	177
360	0.982	177	0.14	8	0.018	82	1.160	177
370	0.982	176	0.12	6	0.017	82	1.120	176
380	0.982	176	0.12	6	0.015	77	1.060	177
390	0.982	176	0.11	9	0.016	72	0.992	177
400	0.982	176	0.10	13	0.018	78	0.958	179
410	0.983	175	0.11	11	0.021	83	1.050	176
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Rev. V1

Table 2. Common Source S-Parameters (VDS = 28 V, ID = 0.65 A) (continued)

f	S <sub>11</sub>		S <sub>11</sub> S <sub>21</sub>		S	12	S <sub>22</sub>		
MHz	S <sub>11</sub>	∠ φ	S <sub>21</sub>	∠ ¢	S <sub>12</sub>	∠ φ	S <sub>22</sub>	∠ φ	
420	0.983	175	0.10	15	0.021	87	1.070	175	
430	0.983	175	0.10	14	0.019	85	1.090	175	
440	0.983	174	0.10	10	0.018	76	1.130	175	
450	0.983	174	0.10	9	0.021	71	1.130	176	
460	0.982	174	0.08	10	0.024	70	1.080	174	
470	0.983	174	0.08	11	0.023	82	0.996	175	
480	0.983	174	0.08	15	0.021	90	0.974	176	
490	0.983	173	0.08	12	0.019	87	0.971	175	
500	0.983	173	0.08	17	0.021	78	1.010	174	

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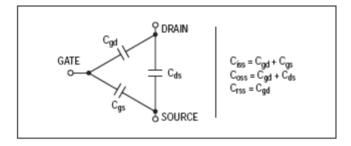
#### RF POWER MOSFET CONSIDERATIONS

#### MOSFET CAPACITANCES

The physical structure of a MOSFET results in capacitors between the terminals. The metal oxide gate structure determines the capacitors from gate—to—drain ( $C_{gd}$ ), and gate—to—source ( $C_{gs}$ ). The PN junction formed during the fabrication of the RF MOSFET results in a junction capacitance from drain—to—source ( $C_{ds}$ ).

These capacitances are characterized as input  $(C_{iss})$ , output  $(C_{oss})$  and reverse transfer  $(C_{rss})$  capacitances on data sheets. The relationships between the inter–terminal capacitances and those given on data sheets are shown below. The  $C_{iss}$  can be specified in two ways:

- Drain shorted to source and positive voltage at the gate.
- Positive voltage of the drain in respect to source and zero volts at the gate. In the latter case the numbers are lower. However, neither method represents the actual operating conditions in RF applications.



#### LINEARITY AND GAIN CHARACTERISTICS

In addition to the typical IMD and power gain data presented, Figure 5 may give the designer additional information on the capabilities of this device. The graph represents the small signal unity current gain frequency at a given drain current level. This is equivalent to  $f_T$  for bipolar transistors.

Since this test is performed at a fast sweep speed, heating of the device does not occur. Thus, in normal use, the higher temperatures may degrade these characteristics to some extent.

#### DRAIN CHARACTERISTICS

One figure of merit for a FET is its static resistance in the full—on condition. This on—resistance, V<sub>DS(on)</sub>, occurs in the linear region of the output characteristic and is specified under specific test conditions for gate—source voltage and drain current. For MOSFETs, V<sub>DS(on)</sub> has a positive temperature coefficient and constitutes an important design consideration at high temperatures, because it contributes to the power dissipation within the device.

#### GATE CHARACTERISTICS

The gate of the RF MOSFET is a polysilicon material, and is electrically isolated from the source by a layer of oxide. The input resistance is very high — on the order of 10<sup>9</sup> ohms — resulting in a leakage current of a few nanoamperes.

Gate control is achieved by applying a positive voltage slightly in excess of the gate-to-source threshold voltage,  $V_{\text{GS(th)}}$ .

Gate Voltage Rating — Never exceed the gate voltage rating. Exceeding the rated  $V_{GS}$  can result in permanent damage to the oxide layer in the gate region.

Gate Termination — The gates of these devices are essentially capacitors. Circuits that leave the gate open–circuited or floating should be avoided. These conditions can result in turn–on of the devices due to voltage build–up on the input capacitor due to leakage currents or pickup.

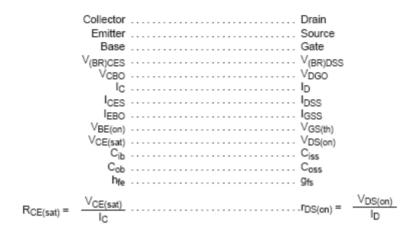
Gate Protection — These devices do not have an internal monolithic zener diode from gate—to—source. If gate protection is required, an external zener diode is recommended.

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Rev. V1

## EQUIVALENT TRANSISTOR PARAMETER TERMINOLOGY



#### PACKAGE DIMENSIONS

